

Chip Scale Review®

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The Future of Semiconductor Packaging

2016 Editorial Calendar

July • August

TSV metals market update	<ul style="list-style-type: none">• ICEPT 2016 Wuhan, China (Aug 16-19)• SEMICON Taiwan Taipei, Taiwan (Sept 7-9)• BiTS China 2016 Suzhou, China (Sept 13)• MEPTEC Medical Electronics Symposium Portland, OR (Sept 14-16)• SEMI European MEMS Summit Stuttgart, Germany (Sept 15-16)
Bonding/debonding for heterogeneous integration	
Photonics packaging	
Packaging for power devices	
Advances in MEMS packaging	
Solder reliability	
Materials development of SiP & IoT	

International Directory of Bonding Equipment for 2.5D and 3D Assembly

Ad Space Close Jun 24 - Ad Materials Close Jul 1

September • October

Lithography for advanced packaging	<ul style="list-style-type: none">• IMAPS 2016 Pasadena, CA (Oct 11-13)• ICPT 2016 Beijing, China (Oct 17-19)• IWLPC-International Wafer-Level Packaging Conference & Exhibition San Jose, CA (Oct 18-20)• SEMICON Europa Grenoble, France (Oct 25-27)
Panel-level packaging	
Trends in TSV technologies	
WLP challenges for MEMS	
Flip-chip packaging	
SiPs	
Cost modeling	

Ad Space Close Sep 9 - Ad Materials Close Sep 16

November • December

3D TSVs	<ul style="list-style-type: none">• MEMS Executive Congress Scottsdale, AZ (Nov 10-11)• SEMICON Japan Tokyo, Japan (Dec 14-16)• International Test Conference (ITC) Fort Worth, TX (Nov 15-17)• RTI 3D ASIP Conference Redwood City, CA (Dec 15-17)
Recent advances in 3D package reliability	
Die stacking	
Heterogeneous integration	
FOWLP	
Failure analysis	
Thermal management of ICs	
Materials for test sockets	
MEMS & sensor technologies	

Ad Space Close Nov 4 - Materials Close Nov 11

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